Smart Direct Drive Ultrasonic Sensor IC with Dual Interface

PRODUCT PREVIEW - Jul 31, 2019

General Description

This device offers the best distance measurement performance in ultrasonic applications. The integrated driver stage directly excites a connected ultrasonic transducer and significantly reduces system cost and size, eliminating the need for a transformer and other external components.

The device receives the reflected signal and processes it for reliable obstacle recognition. This outstanding performance is achieved by an analog frontend with a high sensitive, low noise amplifier and an advanced digital signal processing. In particular, the signal processing with its numerous functions (smart damping, dynamic gain, noise suppression,...) allows very short, long and accurate distance measurements.

The different interfaces support a variety of different applications and architectures, e.g. standard LIN systems with a higher-level control unit or systems without control unit and local bus communication. In addition, the embedded 32-bit microcontroller with re-programmable memory offers maximum flexibility for customer applications and algorithms.

Ordering Information

Product ID	Order Code	Package
E524.36	E52436A52C	QFN20L4

TR

Ultrasonic transducer



elmos LIN1 LIN1 524.36 TR LIN1 O LIN1 C LIN2 GNDA GND (GPIOs e.g. used for UART, SPI. PWM and pin-coding

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Typical Operating Circuit

SUPPLY

Noise suppression features for higher robustness

Features

- Near field data evaluation for close proximity detection
- · Variety of diagnosis functions, e.g. measurement of

4th Generation "Direct Drive" Ultrasonic Sensor IC

Support for various applications and architectures by

• 4x GPIOs (e.g. for UART, SPI, PWM, pin-coding,...)

 Efficient and robust transducer damping algorithm Advanced analog & digital signal processing

Best ultrasonic measurement performance due to

· Widely configurable measurement cycles

• 2x LIN Interfaces (incl. slave node position detection)

- Ringing time and ringing frequency
- Transducer impedance and transducer temperature
- IC temperature and different IC voltages
- Embedded 32-bit microcontroller (Arm[®] Cortex[®]-M0)
 - 32 kByte Flash
 - 4 kByte SRAM

Applications

QFN20L4 package with smallest footprint in the market

• Standard ultrasonic park assist systems (USPA, PAS,...)

Development acc. ISO 26262:2018 (capable up to ASIL-B) ٠

Smart Ultrasonic Sensor IC with DSI Interface

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Contact Information

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